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Resin compsns. for resin-sealed semiconductor devices - comprising epoxy resin, phenolic resin curing agent, amine coupling agent and inorganic filler

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Number of Countries: 001 Number of Patents: 001

Patent Family:

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JP 11158354	A	19990615	JP 97339298	A	19971125	199934 B

Priority Applications (No Type Date): JP 97339298 A 19971125

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 11158354	A		6	C08L-063/00	

Abstract (Basic): JP 11158354 A

A resin compsn. for sealing comprises: (A)an epoxy resin of formula (I); (B) a phenolic resin as curative; (C) an amino-functional coupling agent as a prim. or sec.amine; and (E) 25- 95 wt.% per total resin compsn. of an inorganic filler as essential components. R1-R4 = H or alkyl.

ADVANTAGE - The resin compsns. have good mouldability, storage stability and fluidity with good moisture and solder heat resistance, esp. after dipping in a solder bath, high temp. crack resistance and moisture-resistant reliability. When sealing surface-mounting type semiconductor components, the semiconductor devices have no peeling between sealing resins and semiconductor chips or lead frames, no internal resin cracks, no disconnections owing to electrode corrosion and no leak current generation thanks to water and long reliability.

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Title Terms: RESIN; COMPOSITION; RESIN; SEAL; SEMICONDUCTOR; DEVICE;
COMPRISE; EPOXY; RESIN; PHENOLIC; RESIN; CURE; AGENT; AMINE; COUPLE;
AGENT; INORGANIC; FILL

Derwent Class: A21; A85; E19; E36; G02; L03; U11

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C08K-003/00; C08K-005/54; H01L-023/29; H01L-023/31

File Segment: CPI; EPI